TOSHIBA

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS IV)

# **TPCF8303**

## Notebook PC Applications Portable Equipment Applications

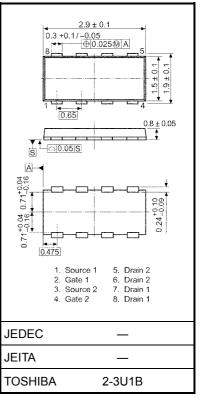
- Low drain-source ON resistance:  $R_{DS}$  (ON) = 58 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 6.0 \text{ S}$  (typ.)
- Low leakage current:  $IDSS = -10 \mu A (max) (VDS = -20 V)$
- Enhancement-model:  $V_{th} = -0.45$  to -1.2 V
  - $(V_{DS} = -10 \text{ V}, \text{ ID} = -200 \text{ }\mu\text{A})$

#### Maximum Ratings (Ta = 25°C)

Cha	Symbol	ymbol Rating		
Drain-source volta	ge	V <sub>DSS</sub>	V <sub>DSS</sub> -20	
Drain-gate voltage	$(R_{GS} = 20 \text{ k}\Omega)$	V <sub>DGR</sub>	-20	V
Gate-source voltag	Gate-source voltage			V
Drain current	DC (Note 1)	I <sub>D</sub>	-3.0	А
Drain current	Pulse (Note 1)	I <sub>DP</sub>	-20 -20 ±8	~
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.35	
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	1.12	w
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.53	vv
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.33	
Single pulse avala	nche energy (Note 4)	E <sub>AS</sub>	0.58	mJ
Avalanche current	alanche current I <sub>AR</sub>			А
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E <sub>AR</sub>	0.11	mJ
Channel temperatu	ıre	T <sub>ch</sub>	150	°C
Storage temperatu	re range	T <sub>stg</sub>	-55~150	°C

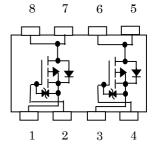
Note: For (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) and (Note 6), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

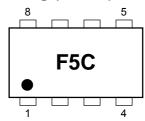


Weight: 0.011 g (typ.)

#### **Circuit Configuration**



# Marking (Note 6)



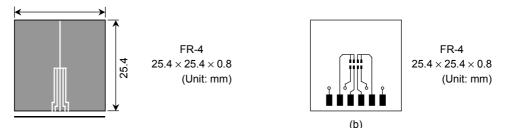
Unit: mm

## **Thermal Characteristics**

Charae	Symbol	Max	Unit		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	92.6	°C/W	
(t = 5 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a)</sub> (2)	111.6		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	235.8	°C/W	
(t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	378.8	0/11	

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)



(b) Device mounted on a glass-epoxy board (b)

- Note 3: a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
  - b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).
- Note 4:  $V_{DD} = -16 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.2 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = -1.5 A
- Note 5: Repetitive rating; Pulse width limited by Max. Channel temperature.
- Note 6: Black round marking "" locates on the left lower side of parts number marking "F5C" indicates terminal No. 1.

Electrical Characteristics (Ta = 25°C)

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 8V, V_{DS} = 0 V$	—		±10	μA	
Drain cut-off curr	ent	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	— — -10		-10	μA	
Drain-source breakdown voltage		V (BR) DSS	$I_{D} = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-20	Ι		v	
	andown vonage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 8 \text{ V}$	-10	-	—	v	
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS}$ = -10 V, $I_D$ = -200 $\mu$ A	-0.45	١	-1.2	V	
		R <sub>DS (ON)</sub>	$V_{GS} = -1.8 V, I_D = -1.5 A$ —		120	250		
Drain-source ON	resistance	R <sub>DS (ON)</sub>	$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -1.5 \text{ A}$	_	63	87	mΩ	
		R <sub>DS (ON)</sub>	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -1.5 \text{ A}$	—	43	58		
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1.5 \text{ A}$	3.0	6.0	_	S	
Input capacitance		C <sub>iss</sub>		_	860	_		
Reverse transfer	capacitance	C <sub>rss</sub>	$V_{DS}$ = -10 V, $V_{GS}$ = 0 V, f = 1 MHz	—	110	—	pF	
Output capacitance		C <sub>oss</sub>			140			
	Rise time	tr	$V_{GS} \stackrel{0}{\xrightarrow{5}}_{-5} V \stackrel{I_{D} = -1.5 \text{ A}}{\xrightarrow{6}}_{-5} V \stackrel{O}{\xrightarrow{6}}_{-5} V \stackrel{O}$	_	5.6	_		
Switching time	Turn-on time	t <sub>on</sub>		_	16	_	20	
Switching time	Fall time	t <sub>f</sub>		_	16	_	ns	
	Turn-off time	t <sub>off</sub>	$V_{DD} \simeq -10 \text{ V}$ Duty $\leq 1\%, t_W = 10  \mu \text{s}$	_	55	_		
Total gate charge (gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≃ -16 V, V <sub>GS</sub> = -5 V,	_	11	_		
Gate-source charge1		Q <sub>gs1</sub>	$I_{\rm D} = -3 {\rm A}$	—	0.9	—	nC	
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	2.7	_		

# Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics Sym		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	—	_	_	-12	А
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = -3.0 \text{ A}, V_{GS} = 0 \text{ V}$	-	—	1.2	V

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